## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Group Art Unit Of Parent: 2827

Examiner Of Parent: David A. ZARNEKE

In Re PATENT APPLICATION OF:

Applicant(s): Takaaki SASAKI

Serial No.

Of Parent:

09/942,962

Filed:

Herewith

For:

SEMICONDUCTOR PACKAGE FOR THREE-

DIMENSIONAL MOUNTING, FABRICATION

METHOD THEREOF, AND SEMICONDUCTOR DEVICE

Docket No.:

TAI 131-D1

INFORMATION **DISCLOSURE STATEMENT** 

February 4, 2004

Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450

Sir:

In accordance with the duty of disclosure, attached is Form PTO-1449 which lists references cited in the parent application 09/942,962. Any relevance of these references can be gleaned from the parent application. The Examiner may wish to consult this parent application during examination of this Divisional Application.

Since this Information Disclosure Statement is being filed with the application, no certification or fee is required, and the requirements of 37 C.F.R. §§1.97 and 1.98 are deemed to be fully met. Consideration of the previously submitted documents is respectfully requested.

February 4, 2004

Date

Respectfully submitted

Robert H. Berdo Jr. Registration No. 38,075 RABIN & BERDO, P.C. CUSTOMER NO. 23995

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RHB:crh

FORM PTO-1449 INFORMATION DISCLOSURE STATEMENT			Atty. Docket: TAI-131D1		Serial No. Of Parent Application: 09/942,962		
•		Applicant: Takaaki SASAKI					
			Filing Date: Herewith (February 4, 2004)		Group Art Unit Of: Parent Application: 2827		
U.S. PATENT DOCUMENTS							
Examiner Initial		Document Number	Date	Name	Class	Sub- Class	Filing Date
	AA	5,726,493	03-1998	Yamashita et al.			
	AB	6,348,728	02-2002	Aiba et al.			
	AC	6,429,528	08-2002	King et al.			
	AD	6,451,624	09-2002	Farnworth et al.			
	AE						
	AF						
	AG						
	АН						
FOREIGN PATENT DOCUMENTS							
		Document Number	Date	Country	Class	Sub- Class	Trans- Lation
	AI	2000-294720	10/20/02	Japan			Abstract
	AJ	11-186492	07/09/99	Japan			Abstract
	AK	07-335783	12/22/95	Japan			Abstract
	AL	09-036273	02/07/97	Japan			Abstract
	AM	09-069587	11/03/97	Japan			Abstract
OTHER (Including Author, Title, Date, Pertinent Pages, etc.)							
	AN	Lau, Flip Chip Technologies, 1996, McGraw-Hill, pp. 27-31, Figures 1.27, 1.29b					
	AO						
Examiner					Date Considered		
EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; draw line through citation if not in conformance and not considered. Include copy of this form with next communication to Applicant.							